

### **SMD Molding Power Inductor**

#### Features

- 1. Magnetically shielded construction, low DC resistance;
- 2. The use of magnetic iron powder ensure capability for large current;
- 3. Low audible core noise:
- 4. Ideal for DC-DC converter applications in hand held personal computer and etc;
- 5. Frequency Range: up to 3.0MHz;
- 6、RoHS compliant。

### **♦** Applications

- 1、Smart phone、MID;
- 2. Next-generation mobile devices with multifunction such as adding color TV and digital movie cameras;
- 3. Flat-screen TVs, blue-ray disc recorders, set top box;
- 4. Notebooks, desktop computers, servers, graphic cards;
- 5. Portable gaming devices, personal navigation systems, personal multimedia devices;
- 6. Automotive systems;
- 7、Telecomm base stations。

### Lead Free Part Numbering

CMLO 0618 H 2R2 M T T (1) (2) (3) (4) (5) (6) (7)

(1) Series Type

(2) Dimension: AXC

(3) Material Code

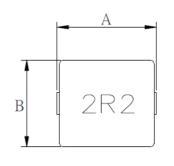
(4) Inductance:  $2R2=2.2\mu H$ ;

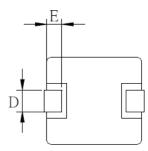
100=10μH; 101=100μH

(5) Inductance Tolerance: M=±20%, Y=±30%

(6) Company Code

(7) Packaging: packed in embossed carrier tape

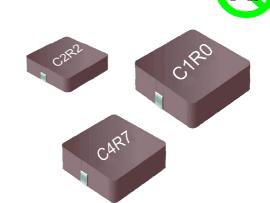






#### **♦** Dimensions

Series	A±0.3(mm)	B±0.3 (mm)	C (mm)	D±0.2 (mm)	E±0.2 (mm)
CMLO0618H	7.1	6.6	1.8 Max	3.0	1.5





### **♦** Specification

Part Number	INDUCTANCE (I		dc Ω)	Test a	HEAT RATING CURRENT(Idc)	SATURATION CURRENT(Isat)		
	Lo(   H)	Тур.	Max	condition	DC AMPS1 (Typ.)	DC AMPS2 (Typ.)		
CMLO0618H Series								
CMLO0618HR10MTT	0.10	2.0	2.5	100KHz/1V	18.0	45.0		
CMLO0618HR33MTT	0.33	5.2	6.8	100KHz/1V	12.0	22.0		
CMLO0618HR47MTT	0.47	7.3	8.4	100KHz/1V	11.0	18.0		
CMLO0618HR68MTT	0.68	10.8	12.7	100KHz/1V	9.5	17.0		
CMLO0618H1R0MTT	1.0	14.5	17.0	100KHz/1V	7.0	14.0		
CMLO0618H2R2MTT	2.2	31.0	35.0	100KHz/1V	6.0	13.0		
CMLO0618H3R3MTT	3.3	56.0	60.0	100KHz/1V	3.5	10.0		
CMLO0618H4R7MTT	4.7	68.0	72.0	100KHz/1V	3.5	5.0		
CMLO0618H6R8MTT	6.8	71.0	95.0	100KHz/1V	2.8	3.5		

#### NOTES:

- 1. DC current (ldc) that will cause an approximate  $\triangle T$  of 40°C
- 2. DC current (Isat) that will cause Lo to drop approximately 20%
- 4. Operating Temperature Range -55°C to +150°C
- 5. The part temperature (ambient + temp rise) should not exceed  $150^{\circ}$ C under the worst operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

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## **♦** Reliability Test

Item	Specification and Requirement	Test Method		
Solderability	No case deformation or change in apperarance     New solder coverage More than 90%	1.Preheat: 155℃±5℃, 60S±2S 2.Tin: lead-free. 3.Temperature:245℃±5℃, flux 3.0S±0.5S.		
Mechanical shock	<ul><li>1. No case deformation or change in apperarance</li><li>2. △L/Lo≤±10%</li></ul>	<ol> <li>Acceleration: 100G</li> <li>Pulse time: 6ms</li> <li>3 times in each positive and negative direction of mutual perpendicular directions</li> </ol>		
Mechanical vibration	<ul><li>1. No case deformation or change in apperarance</li><li>2. △L/Lo≤±10%</li></ul>	1. The test samples shall be soldered to the board. Then it shall be submitted to below test conditions  Fre. Range 10~55Hz  Total Amplitude 1.5mm  Sweeping Method 10Hz to 55Hz to 10Hz  Time For 2 hours on each X,Y,Z axis.  2. Recovery: At least 2 hours of recovery under the standard condition after the test, followed by the measurement within 24 ±2 hours.		
Thermal Shock	Inductance change: Within ± 10% Without distinct damage in appearance  1. First -55℃ for 30 minute minutes as 1 cycle. Go 2. Max transfer time is 2 n 3. Measured at room temp 24±2 hours			
Humidity Resistance	Inductance change: Within ± 10% Without distinct damage in appearance	1.Reflow 2 times, 2.85℃,85%RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours		
Low temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	<ol> <li>Temperature: -55 ± 2°C</li> <li>Time: 1000 hours</li> <li>Measured at room temperature after placing for 24±2 hours</li> </ol>		
High temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	<ol> <li>Temperature: +125 ± 2°C</li> <li>Time: 1000 hours</li> <li>Measured at room temperature after placing for 24±2 hours</li> </ol>		

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	Inductance change:	1、Run through IR reflow for 2 times;
	Within ± 10% Without distinct damage	2. Place the 100mm X 40mm board into a fixture
	in appearance	similar to the one shown in below Figure with the
		component facing down
		3. The apparatus shall consist of mechanical means
		to apply a force which will bend the board (D) x = 2
		mm minimum.
		4. The duration of the applied forces shall be 60±5
Board Flex		sec. The force is to be applied only once to the oard.
		Support Solder Chip Printed circuit board before to
		Printed circuit board under test  Printed circuit board under test  Displacement
	No removal or split of the termination or	1. The test samples shall be soldered to the board
	other defects shall occur.	2. Push the product vertically from the side of the
		sample using the thrust tester.
		3、Automotive electronics: 17.7N,60S±1s,X,
Terminal		Ydirect.
Strength		X direct
		Y direct

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### **♦** Recommended Soldering Technologies

#### (1) Re-flowing Profile

Preheat condition: 150 ~200 °C/60~180sec.

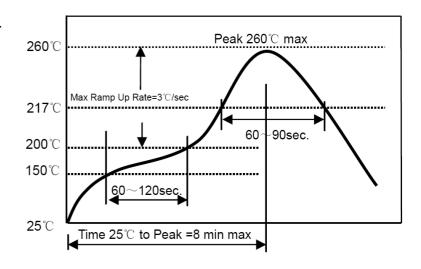
Allowed time above 217°C: 80~120sec.

Max temp: 260°C

Max time at max temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max



#### (2) Iron Soldering Profile

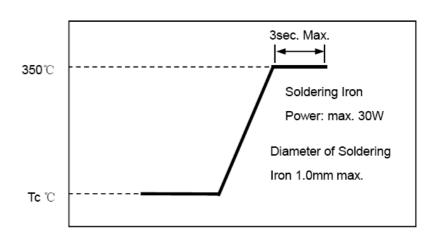
Iron soldering power: Max. 30W

Pre-heating: 150 °C/60sec.

Soldering time: 3sec. Max.

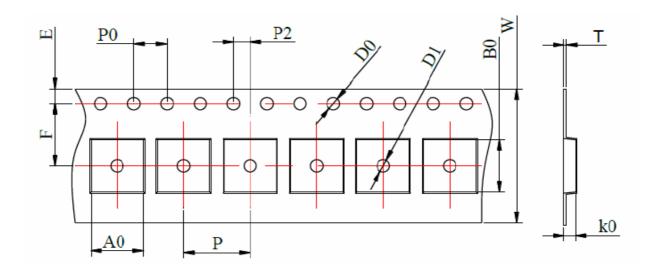
Solder paste: Sn/3.0Ag/0.5Cu

Max.1 times for iron soldering



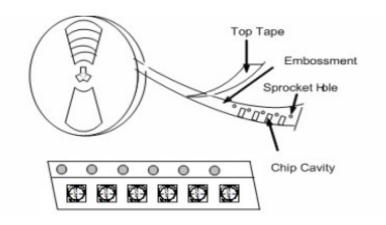
### **◆**Packaging Information

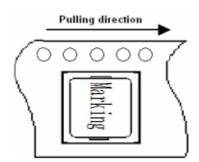
(1) Tape Packaging Dimensions (Unit: mm)



Typo					Тар	e dimer	nsions (n	nm)				
Туре	W	Р	P0	P2	D0	D1	Т	A0	В0	K0	Е	F
CMLO0618	16 ±0.3	12 ±0.1	4 ±0.1	2 ±0.1	1.5 ±0.1	1.5 ±0.1	0.35 ±0.05	6.9 ±0.1	7.5 ±0.1	2.1 ±0.1	1.75 ±0.1	7.5 ±0.1

#### **Taping Drawings (UNIT:mm)**

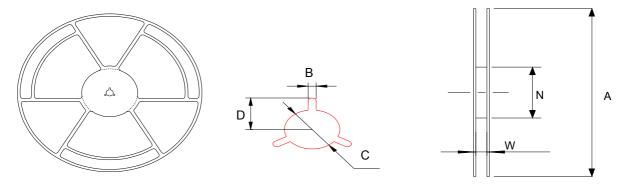




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#### (2) Reel Dimensions (Unit: mm)



А	W	N	В	С	D
330+2.0	16.8+0.2	97+0.5	2.2+0.5	13.2±0.2	10.75±0.25

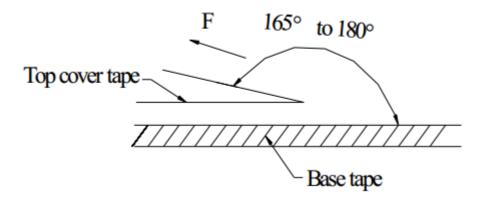
#### (3) Packaging Quantity(PCS)

Туре	Standard Quantity				
	Reel	Inner box	Carton box		
CMLO0618	2000 pcs / reel	3Reel / box (6000 pcs)	4 Middle boxes, (24000 pcs)		

#### (4) Peel force of top cover tape

The peel speed shall be about 300mm/minute

The peel force of top cover tape shall be between 0.1 to 1.3 N



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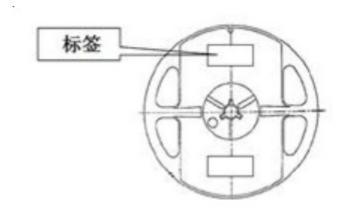
#### (5) Reel Label

Label on the reel

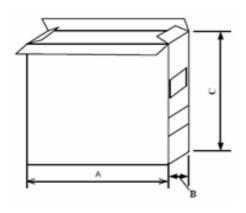
- · Customer's part Number
- Lot Number
- Quantity
- date code

#### Shipping Label

- Customer's part Number
- · Manufacturer's part Number
- Quantity
- · date code

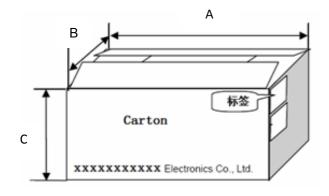


#### (6) Inner Box



Packaging type	A (mm)	B (mm)	C (mm)
lnner box	335	70	340

#### (7) Carton



Packaging type	A (mm)	B (mm)	B (mm)
type	360	360	360